Information for Lot 9 of ErP (Ecodesign)

This addendum addresses European Union (EU) Ecodesign requirements for servers and storage products. All data and ratings within this addendum are in reference only to the Supermicro product(s) in the manual. The below information conforms to requirements laid down in Annex II of the Commission Regulation 2019/424.

3(1)(a): See Section 1.1 of the system manual for the product type.

3(1)(b): See the title page and preface of the system manual for the trademark and manufacturer's address.

3(1)(c): See the title page of the system manual for product model number(s).

3(1)(d): See the serial number on the physical system to determine the year of manufacture.

3(1)(e-j): **PSU Efficiency and Power Factor Value (Table) (From 80 Plus report)**

PSU Model #: PWS-6K61G-2R Watts: 6600W	**PSU Efficiency**				**Power Factor**
% of Rated Load	**10 %**	**20 %**	**50 %**	**100 %**	**50 %**
Single Output (AC-DC)	90.88%	94.68%	96.27%	95.33%	0.9920

System (EUT) Efficiency in Idle State Power (Table)

Representative Configurations	**Measured Idle State Power (W)**	**Calculated Idle Power Allowance (W)**
High-End Performance Configuration	622.2	992.4331
Typical Configuration	N/A	N/A
Low-End Performance Configuration	510.0	361.6628

System (EUT) Efficiency in Active State Power (Table)

Representative Configurations	**Active State Efficiency Score (Effserver)**	**Minimum Active State Efficiency for 2-Socket Server**
High-End Performance Configuration	69.5	9.5
Typical Configuration	N/A	
Low-End Performance Configuration	22	

3(1)(k): The operating condition class is **A2**.

	Dry bulb temp °C		Humidity range, non-condensing			
Operating condition class	Allowable range	Recom-mended range	Allowable range	Recommended range	Max dew point (°C)	Maximum rate of change (°C/hr)
A1	15- 32	18-27	– 12 °C Dew Point (DP) and 8 % relative humidity (RH) to 17 °C DP and 80 % RH	– 9 °C DP to 15 °C DP and 60 % RH	17	5/20
A2	10-35	18-27	– 12 °C DP and 8 % RH to 21 °C DP and 80 % RH	Same as A1	21	5/20
A3	5-40	18-27	– 12 °C DP and 8 % RH to 24 °C DP and 85 % RH	Same as A1	24	5/20
A4	5-45	18-27	– 12 °C DP and 8 % RH to 24 °C DP and 90 % RH	Same as A1	24	5/20

3(1)(l): The idle state power at the higher boundary temperature of the operating conditions class is 1136.5 W.

3(1)(m): The active state efficiency and performance is 69.5.

3(1)(n): There are two methods by which a user can securely delete data from this system. The user performing secure data deletion should be an IT professional.

The first is with a Unified Extensible Firmware Interface (UEFI) shell utility. This utility works on X10/X11/X12/X13/X14/H11/H12/H13/H14/M11 motherboard series with onboard SATA/NVMe devices. Any user may access and download this utility through following link:
https://www.supermicro.com/about/policies/disclaimer.cfm?url=/wftp/utility/Lot9_Secure_Data_Deletion_Utility/

Download the shell utility package and extract it to a USB flash drive, then plug the drive into the server for which secure data deletion is necessary. Then turn the system on. Navigate to the BIOS setup menu, then place the server system into the UEFI shell environment. Follow the instructions in the README file to invoke the utility and complete the deletion.

The second method is through the secure data deletion tool provided by the original manufacturer of the hard drive. This should be used in a scenario where the shell utility is not applicable. Each manufacturer should have the tool available on their website. If needed, please look on the hard drive label for the name of the manufacturer and model information.

3(1)(o): List of recommended combinations of blade servers with chassis: N/A.

3(1)(p): List of all current SKUs within this product family: SYS-822GS-NBRT.

3(3)(a): There is no use of cobalt in batteries in this product.

The indicative weight range of neodymium in the HDD is 0.0 if manufactured by Western Digital, and is between 5-25 grams if manufactured by Seagate.

3(3)(b): Please see the disassembly instructions on the next page.

Illustrated System Disassembly Instructions

Please note: All the illustrations in the below disassembly instructions are for demonstration only. Components shown here may not match exactly with the components in your system.

CAUTION: Always power off the system and unplug the power cord(s) first before disassembling the system!

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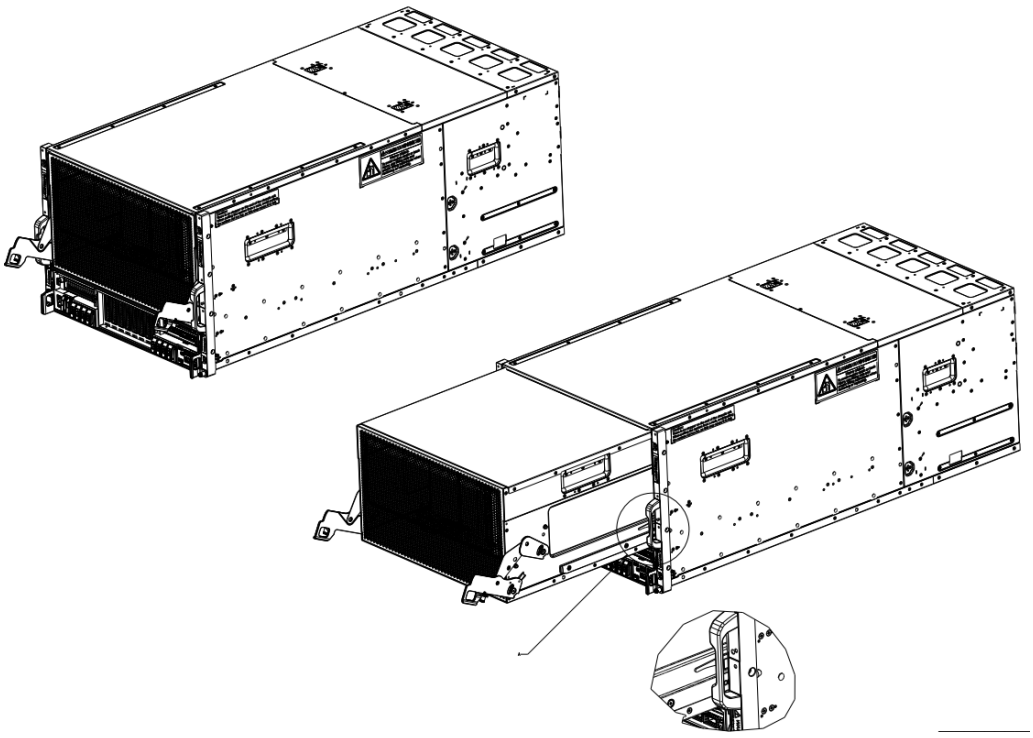
1. GPU Drawer Cover

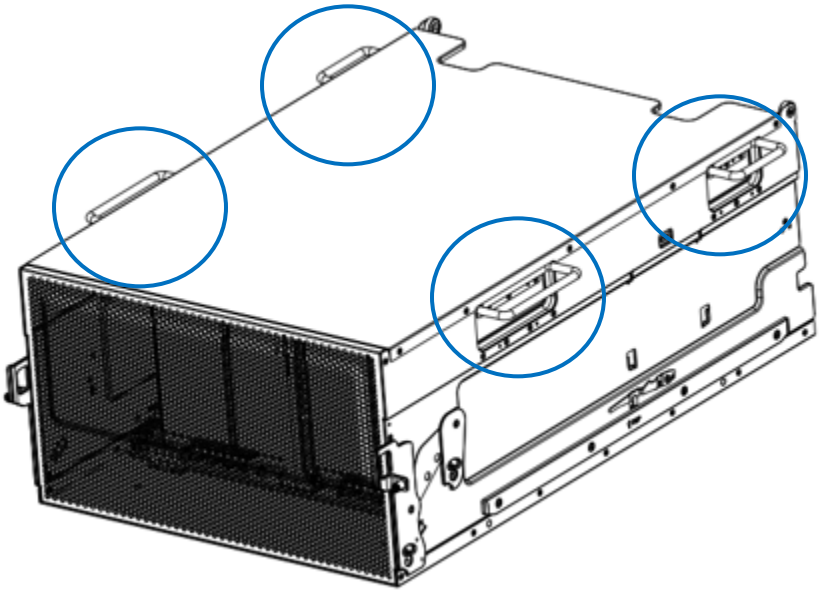
Type and number of fastenings: Eight (8) Phillips screws.

Tools required: Screwdriver with PH2 bit.

Procedure:

1. Remove the drawer from the chassis.
2. Remove the screws that secure the cover to the GPU drawer.
3. Slide the cover toward the rear of the chassis.
4. Lift the top cover off the chassis.





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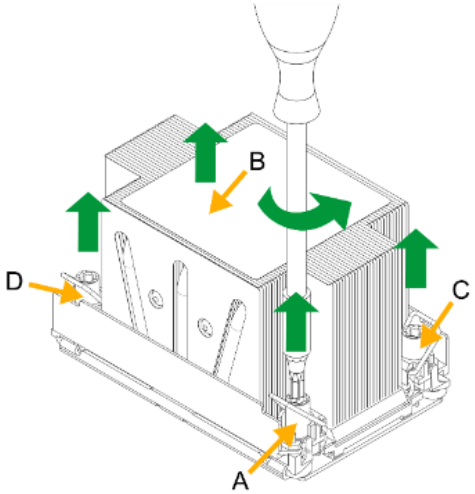
2. Processor

Type and number of fastenings: Four (4) T30 Torx screws.

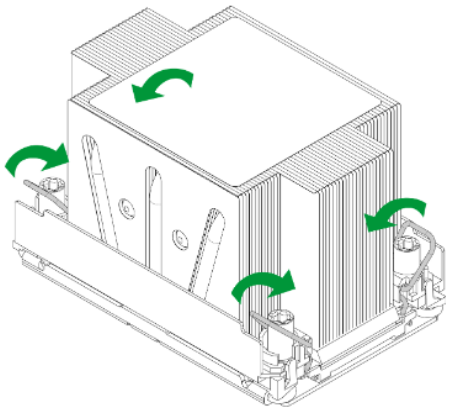
Tools required: Screwdriver with T30 Torx bit.

Procedure:

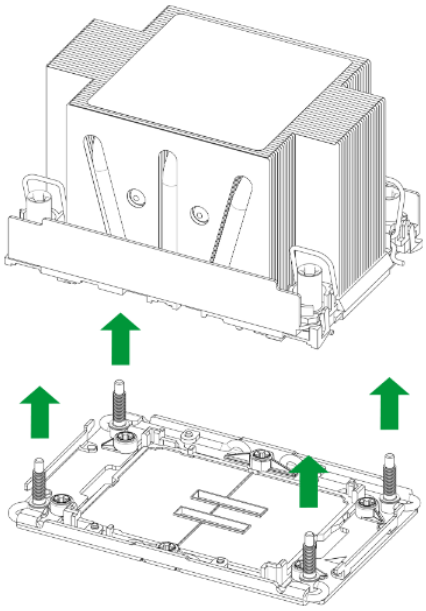
1. Use a screwdriver to loosen the four screws in a diagonal pattern.



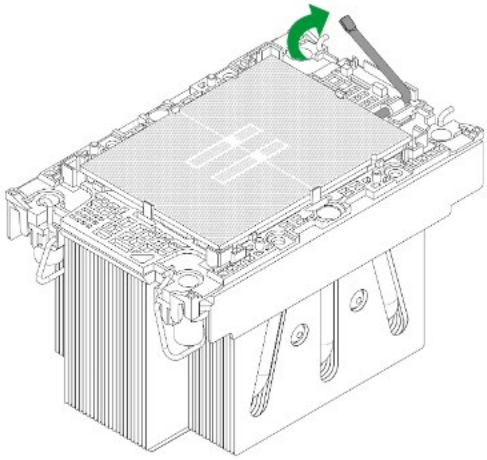
2. Press the four rotating wires outward to unlatch the processor heatsink module from the socket.



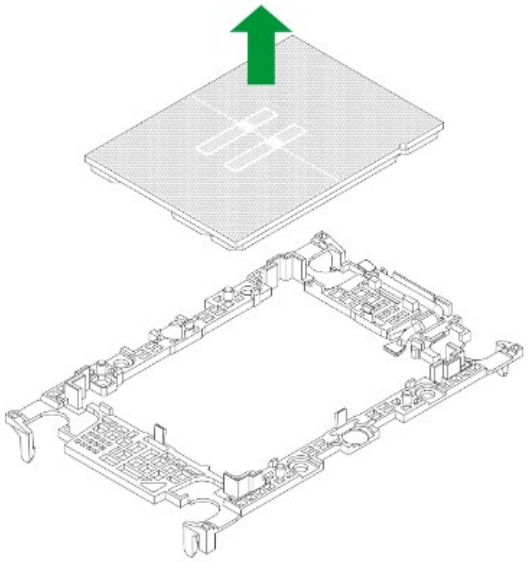
3. Gently lift the processor heatsink module upward to remove it from the socket.



4. To remove the processor from the heatsink, gently lift the lever from the processor carrier.



5. To remove the processor, move the lever to its unlocked position and gently remove the processor.



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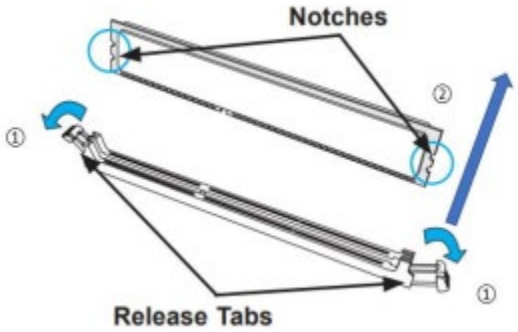
3. Memory

Type and number of fastenings: Two (2) latches per memory module.

Tools required: None.

Procedure:
1. Press both release tabs on the ends of the memory module to unlock it.
2. After loosening the module, carefully remove it from the memory slot.



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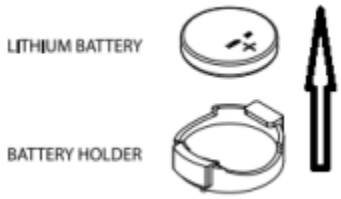
4. Battery

Type and number of fastenings: One (1) latch.

Tools required: None.

Procedure: Push the clamp aside to release the battery, then lift the battery out of the holder.



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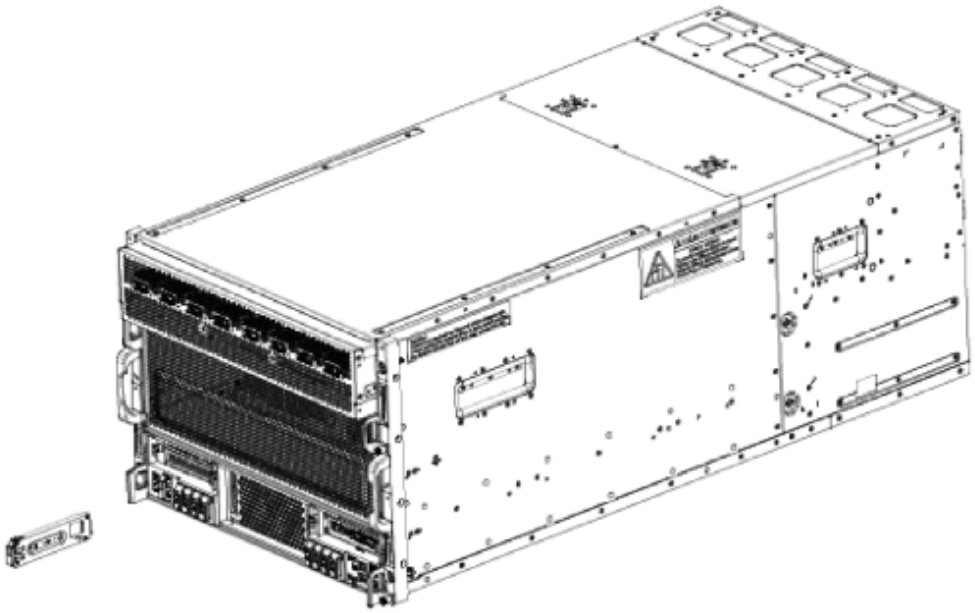
5. M.2 Drive

Type and number of fastenings: One (1) Phillips screw.

Tools required: Screwdriver with PH2 bit.

Procedure:
1. Locate and lift the M.2 tray latch.
2. Unplug the M.2 tray.
3. Unscrew the M.2 drive from the tray.

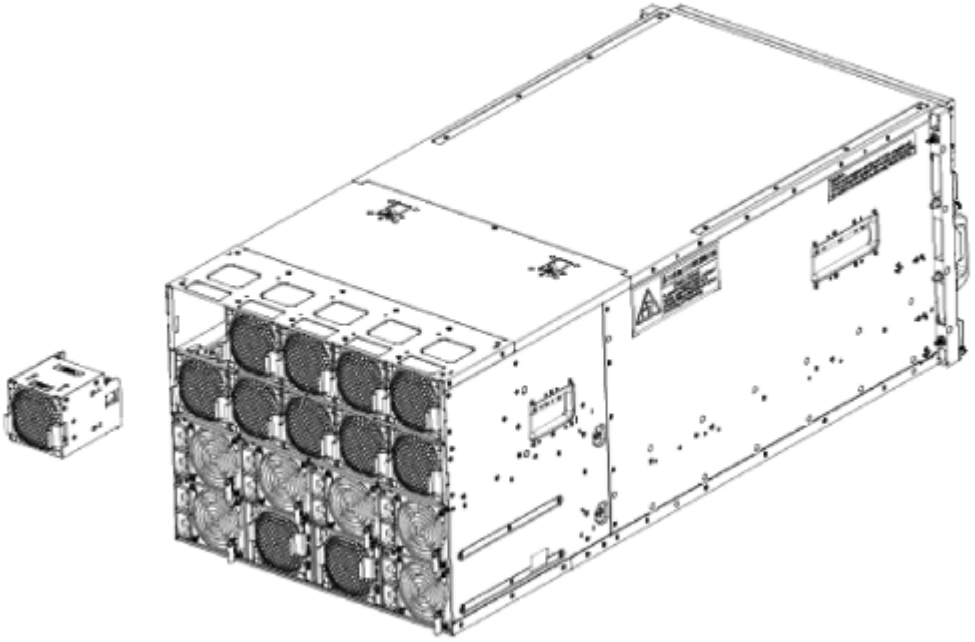


6. Fans

Type and number of fastenings: Two (2) latches.

Tools required: None.

Procedure:
1. Remove the fan from the chassis by squeezing the two release tabs together.
2. Pull the fan out.

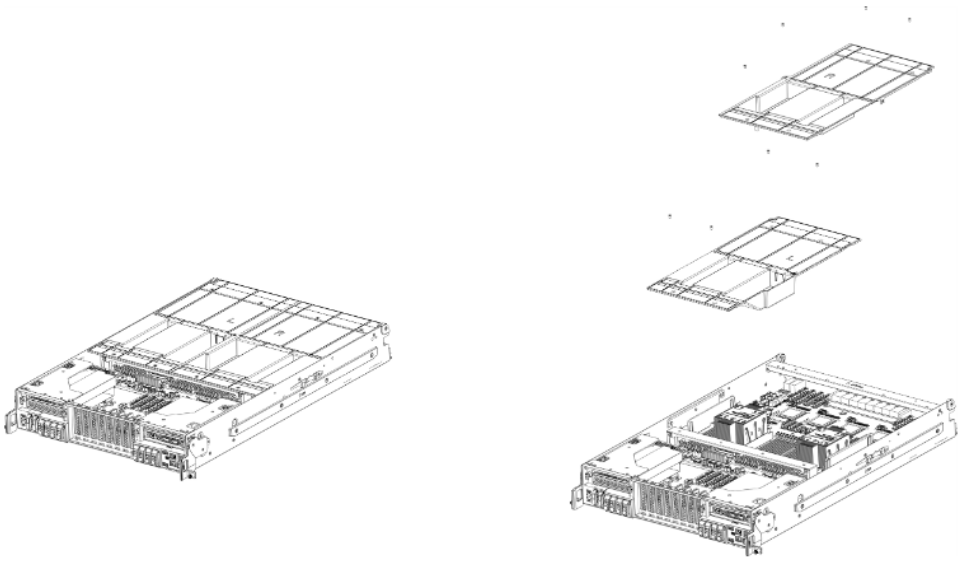


7. Air Shroud

Type and number of fastenings: Eight (8) Phillips screws.

Tools required: Screwdriver with PH2 bit.

Procedure: Lift the air shroud away from the motherboard.

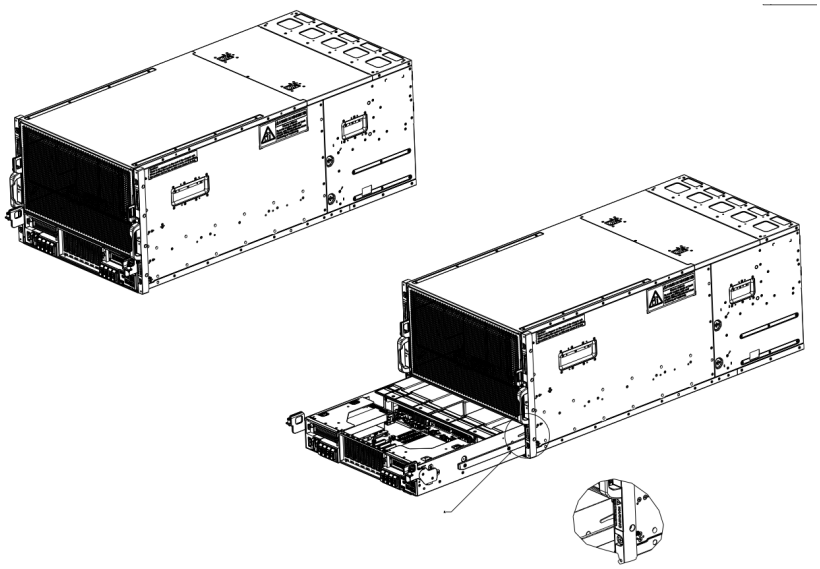


8. CPU Drawer

Type and number of fastenings: Two (2) Phillips screws.

Tools required: Screwdriver with PH2 bit.

Procedure:
1. Locate the two levers on the left and the right sides of the CPU drawer.
2. Loosen the screws securing the levers.
3. Pull both levers down.
4. Use the levers to slide the drawer out of the chassis.

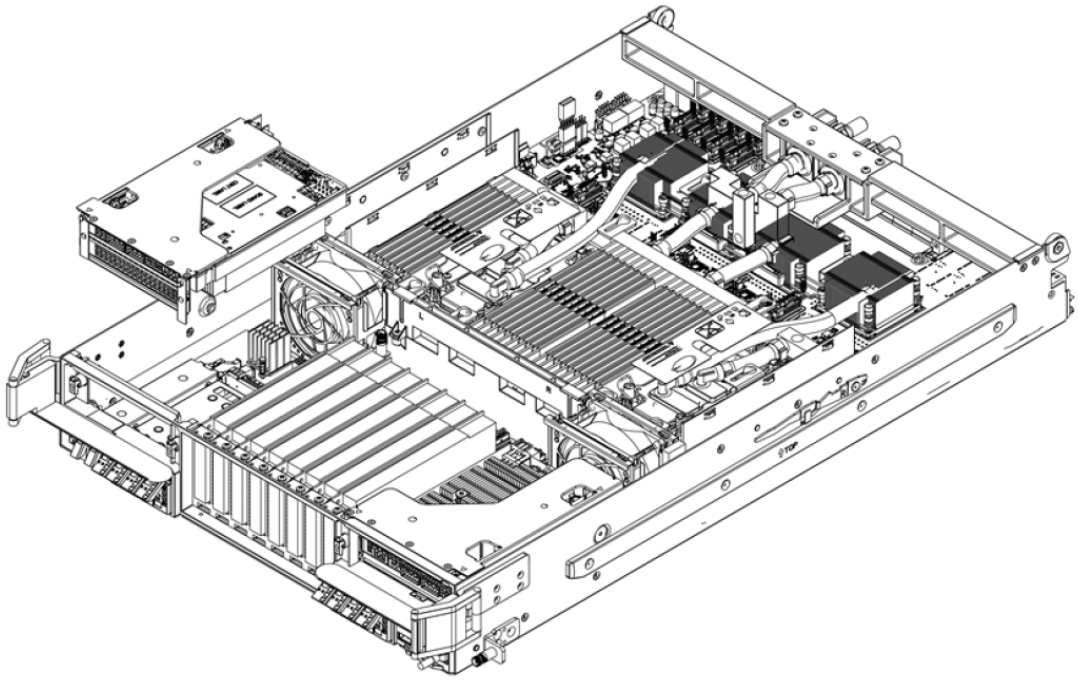


9. CPU Drawer Front Riser Card

Type and number of fastenings: One (1) Phillips screw per riser card.

Tools required: Screwdriver with PH2 bit.

Procedure:
1. Lift the riser card brackets away from the CPU tray.
2. Remove the screws to separate the riser cards from the riser card brackets.



10. Power Supply Module

Type and number of fastenings: One (1) latch per module.

Tools required: None.

Procedure:
1. Unplug the power cord from the power supply.
2. Push the release tab on the back of the power supply module to the side and pull the module straight out.